



Material Content Data Sheet



Sales Product Name		BCR 553 E6327		Issued		29. August 2013		
MA#		MA000238832						
Package		PG-SOT23-3-4		Weight*		9.08 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		15	
	noble metal	gold	7440-57-5	0.013	0.14		1438	
	inorganic material	silicon	7440-21-3	0.112	1.23	1.37	12283	13736
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		995	
	inorganic material	silicon	7440-21-3	0.001	0.01		66	
	non noble metal	titanium	7440-32-6	0.003	0.03		332	
	non noble metal	copper	7440-50-8	3.001	33.04	33.18	330382	331775
wire	noble metal	gold	7440-57-5	0.021	0.23	0.23	2313	2313
encapsulation	organic material	carbon black	1333-86-4	0.091	1.00		10001	
	inorganic material	antimonytrioxide	1309-64-4	0.136	1.50		15002	
	plastics	brominated resin	-	0.170	1.88		18752	
	plastics	epoxy resin	-	1.419	15.63		156270	
	inorganic material	silicondioxide	60676-86-0	3.861	42.50	62.51	425054	625079
leadfinish	non noble metal	tin	7440-31-5	0.136	1.50	1.50	15019	15019
plating	noble metal	silver	7440-22-4	0.110	1.21	1.21	12078	12078
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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